Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.0177”**

**.0177”**

**ANODE**

**BACKSIDE IS CATHODE**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .010**

**Backside Potential: Cathode**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .0177” X .0177” DATE: 7/13/22**

**MFG: FAIRCHILD THICKNESS .008” P/N: BZX55C16V**

**DG 10.1.2**

#### Rev B, 7/19/02